

FORM PTO-1449 U.S. Department of Commerce
Patent and Trademark Office

Attorney Docket Number
9134-32CT

Serial No.
To Be
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LIST OF DOCUMENTS CITED BY APPLICANT

(Use several sheets if necessary)

Applicants: Dhuler

Filing Date Concurrently Herewith

Group
Unknown

1033 U.S. PTO
09/891700
06/26/01

U. S. PATENT DOCUMENTS

Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date if Appropriate
DC	1	3,609,593	9/28/71	Bell, et al.	331	156	
↑	2	5,309,056	5/3/94	Culp	310	306	
	3	5,467,068	11/14/95	Field, et al.	335	4	
	4	5,483,799	1/16/96	Dalto	62	3,7	
	5	5,644,177	7/1/97	Guckel et al.	310	40MM	
	6	5,722,989	3/3/98	Fitch	606	205	
	7	5,796,152	8/18/98	Carr, et al.	257	415	
	8	5,813,441	9/29/98	Dewispelaere	139	455	
	9	5,862,003	1/19/99	Saif, et al.	359	871	
	10	1,258,368	3/19/98	Smith	310	307	
	11	1,658,669	9/19/96	Cohn et al.	310	306	
	12	3,213,318	2/1928	Glenn	310	306	
	13	4,806,815	10/1965	Honna	310	307	
	14	5,184,269	2/1989	Shimada, et al.	361	24	
	15	5,355,712	2/1993	Peterson, et al.	73	4R	
	16	5,441,343	10/1994	Pylkki, et al.	374	137	
	17	5,475,318	8/1996	Marcus, et al.	324	762	
	18	5,558,304	12/1995	Adams	244	134A	
	19	5,600,174	9/1996	Reay, et al.	257	467	
	20	5,629,665	2/1997	Kaufmann, et al.	338	18	
	21	5,659,285	5/1997	Takeda	337	389	
	22	5,179,499	8/19/97	MacDonald et al.	361	313	
	23	5,261,747	1/12/93	Deacutis et al.	374	137	
	24	5,367,584	11/16/93	Ghezze et al.	385	17	
	25	5,536,988	11/22/94	Zhang et al.	310	309	
DC	26	5,602,955	7/16/96	Haake	385	136	
			2/11/97				

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DC	27.	5,881,198	3/9/99	Haake	385	136
↑	28.	5,606,635	2/25/97	Haake	385	53
↓	29.	5,909,078	6/1/99	Wood et al.	310	307
↓	30.	5,726,073	3/10/98	Zhang et al.	437	228
↓	31.	5,316,979	5/31/94	MacDonald et al.	437	203
↓	32.	5,994,816	11/99	Dhuler et al.	310	307
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↓	38.	DE 38 09 597	10/5/89	Abstract Only	—	—	
↓	39.	EP 0 469 749	2/5/92	EPO	—	—	
↓	40.	EP 0665 950	8/2/95	EPO	—	—	
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↑	44.	Phipps, Thesis: "Design and Development of Microswitches for Micro-Electro-Mechanical Relay Matrices," Air Force Inst. Of Tech., Wright-Patterson AFB, OH School of Engineering, 1996
↓	45.	Yamagata, et al., "A Micro Mobile Mechanism Using Thermal Expansion and Its Theoretical Analysis-A Comparison with Impact Drive Mechanism Using Piezoelectric Elements," <u>Proceedings of the IEEE Micro Electro Mechanical Systems</u> , 1994, pp. 142-147
↓	46.	Oh, et al. "Thin Film Heater on a Thermally Isolated Microstructure," <u>Smart Materials Fabrication and Materials for Micro-Electro-Mechanical Systems</u> , 1992, pp. 277-282.
↓	47.	Safranek, "The Properties of Electrodeposited Metals & Alloys," <u>Amer. Electroplaters & Surface Finishers Society</u> , 1986, pp. 295-315
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DL		Microstructures," <u>Transducers '95 - Eurosensors IX</u> , the 8th International Conference on Solid State Sensors and Actuators, and Eurosensors IX, Stockholm, Sweden, June 25-29, 1995, pp. 556-559	
↑	49.	Noworolski et al., "Fabrication of SOI Wafers with Buried Cavities Using Silicon Fusion bonding and Electrochemical Etchback," <u>Transducers '95 - Eurosensors IX</u> , The 8th International Conference on Solid State Sensors and Actuators, and Eurosensors IX, Stockholm, Sweden, June 25-29, 1995, pp. 71-74	
	50.	<i>Single Crystal Silicon Actuators and Sensors Based on Silicon Fusion Bonding Technology, Semiannual Progress Report 1, Advanced Research Projects Agency, Lucas NovaSensor, Contract Number DAAL 01-94-C-3411, April-July 1994</i>	
	51.	<i>Single Crystal Silicon Actuators and Sensors Based on Silicon Fusion Bonding Technology, Semiannual Progress Report 2, Advanced Research Projects Agency, Lucas NovaSensor, Contract Number DAAL 01-94-C-3411, July 1994-January 1995</i>	
	52.	<i>Single Crystal Silicon Actuators and Sensors Based on Silicon Fusion Bonding Technology, Semiannual Progress Report, Advanced Research Projects Agency, Lucas NovaSensor, Contract Number DAAL 01-94-C-3411, January-July 1995</i>	
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	54.	J.W. Judy et al., <i>Surface Micromachined Linear Thermal Microactuator</i> , <u>International Electron Devices Meeting 1990. Technical Digest (CAT. No. 90CH2865-4)</u> , December 1990, New York, New York, pp. 629-632	
	55.	Fedder et al., <i>Multimode Digital Control of a Suspended Polysilicon Microstructure</i> , <u>Journal of Microelectromechanical Systems</u> , December 1986, Vol. 5, No. 4, pp. 283-297	
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DL	57.	Lin et al., <i>Vertically Driven Microactuators by Electrothermal Buckling Effects</i> , <u>Sensors and Actuators</u> , November 1998, Vol. 17, Nos. 1-2, pp. 35-39	

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